

ABSTRACT OF THE DISCLOSURE

Electronic contacts, including spherical cores and attachment layers on the cores, are provided for attaching a semiconductor package substrate to a printed circuit board. The spherical cores are made of high-melting-temperature copper, and the attachment layers are made of a low-melting-temperature eutectic. The attachment layers melt in a reflow process. The spherical cores do not melt, and thereby control movement or "collapsing" of the package substrate toward the printed circuit board.

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